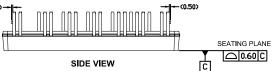
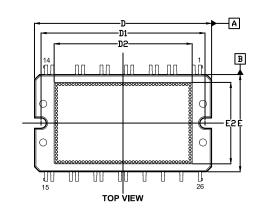
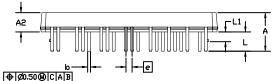


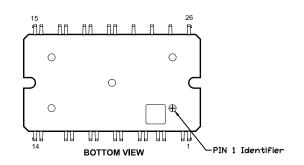
(0.50)







SIDE VIEW



NOTES:

AЗ

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END VIEW

DIP26 67.8x40 CASE 181AD ISSUE B

- 1. Dimensioning and tolerancing as per ASME Y14.5M, 2009
- 2. Controlling Dimension: Millimeters
- 3. Dimensions are exclusive of Burrs, Mold Flash, and Tiebar extrusions
- 4. Dimensions "b" and "c" apply to plated leads
- 5. Position of the leads is determine at the root of the lead where it exits the package body

DIM	MILLIMETERS			
	MIN	NOM	MAX	
А	15.50	16.00	16.50	
A2	7.80	8.00	8.20	
A3	6.00 REF			
b	1.10	1.20	1.30	
с	0.70	0.80	0.90	
D	72.70	73.20	73.70	
D1	67.30	67.80	68.30	
D2	57.30 REF			
Е	39.70	40.20	40.70	
E1	46.70	47.20	47.70	
E2	33.87 REF			
е	2.54 BSC			
F	4.00	4.20	4.40	
L	8.00 REF			
L1	3.50	4.00	4.50	
М	4°	5°	6°	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

ZZZ = Assembly Lot Code

AT = Assembly & Test Location

Y = Year

WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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